Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.018”**

**ANODE**

**.018”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .011” x .011” min.**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .018” X .018” DATE: 5/9/22**

**MFG: SILICON SUPPLIES THICKNESS .010” P/N: 1N6326**

**DG 10.1.2**

#### Rev B, 7/19/02